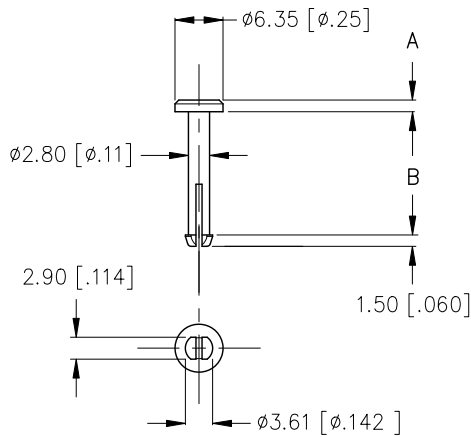
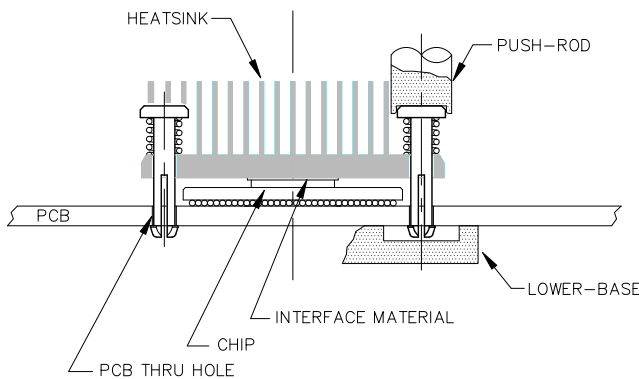
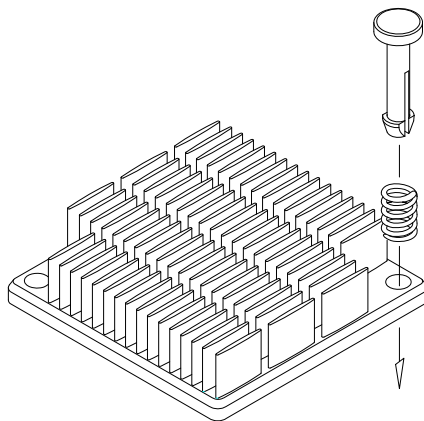




THE PIP3.175 SERIES MOUNTS THE HEATSINK TO THE PCB USING A SPRING. OBTAINING ADEQUATE PRESSURE REQUIRED FOR THERMAL INTERFACE MATERIAL PERFORMANCE IS EASILY ATTAINED BY CHOOSING AN APPROPRIATE SPRING (NOT INCLUDED.).



P/N	PART NAME	A	B
S001YZ3M	PIP3.175x7.0 [TH]	0.89 [.035]	7.00 [.276]
S001YZ1H	PIP3.175x8.5 [TH]		8.50 [.335]
S001YZ10	PIP3.175x9.8 [TH]	1.27 [.050]	9.80 [.386]
S001YZ0T	PIP3.175x11 [TH]		11.00 [.433]
S001YZ0N	PIP3.175x11.5	1.55 [.061]	11.50 [.453]
S001YZ1P	PIP3.175x13.2		13.20 [.520]
S001YZ0M	PIP3.175x14.3		14.30 [.563]
S001YZ0Y	PIP3.175x18.8		18.80 [.740]
S001YZ0X	PIP3.175x20.3		20.30 [.799]



- MATERIAL : BRASS (ROHS COMPLIANT)
C6801 SAN-ETU METALS BZ5
OR EQUIVALENT
- DIMENSIONS mm [inch]

REFERENCES:

- HEATSINK:
REQUIRES HEATSINK HOLE DIAMETER OF 3.45 [.136] IF "PIP3.175 + SPRING" NEEDS TO BE CAPTIVE. (WHEN BASE THICKNESS IS LESS THAN 2 mm OR SPRING IS PRE-COMPRESSED, HEATSINK HOLE DIAMETER 3.30 IS RECOMMENDED.)
- BOARD:
REQUIRES $\phi 3.175 \pm 0.05$ [$\phi .125 \pm .002$] THRU HOLES IN BOARD.
- INSTALLATION:
THE SPRING SHOULD NOT BE COMPRESSED TO SOLID LENGTH DURING INSTALLATION AND SHOULD BE SUPPORTED BY THE LOWER-BASE. PUSH-ROD AND LOWER-BASE NEEDS TO BE OBTAINED/PRODUCED LOCALLY.

APR 2019